DATA SHEET

Part No.	AN41240A				
Package Code No.	HSOP056-P-0300B				

Publication date: May 2007 SDC00072AEB

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AN41240A

Motor drive IC for Optical Disk

Overview

The AN41240A is a single chip IC that uses single-hall-sensor drive on the input side of the spindle motor drive block and low-noise direct PWM drive of sine wave on the output side, incorporating a PWM 6-channel driver necessary for optical pickup and mechanism driving.

It is effective for reducing noise, vibration and power consumption of the optical disk drive.

Features

• 1-hall-sensor, 3 phase full-wave and less-noise Direct-PWM driving for Spindle motor driver.

• The actuator (focus, tracking, tilt) drive blocks use linear input and direct PWM drive technique. Moreover, the driver are low in power consumption.

Sled (stepping) motor and loading motor drive blocks use linear input and direct PWM drive technique.
 Less external components are used as the current detection resistors are built-in.

• Independent power supply pins are provided for each of the spindle motor, actuator, sled (stepping) motor, and loading motor drive channels.

• Functions : Motor drive for optical disk /Actuator drive

Spindle motor driver, Actuator (Focus, Tracking, Tilt) driver,

Sled (Stepping) motor driver, Loading motor driver

Drive voltage : 8 V (V_{MSP}, V_{MST}), 5 V (V_{DD}, V_{MAC}), 8 V/5 V (VMLO)
 Additional features : Built-in Stand-by function (Spindle and Ch.1 to Ch.6 ALL mute)

1 time /3 times FG output frequency switch

Spindle Torque Limit switch

Short brake / Reverse brake / Auto brake switch Normal Torque / Low-Torque Mode switch

Bias pin for Hall elements Thermal shutdown

Loading power supply selectable, 8 V / 5 V.

Sled (Stepping) gain switch

Applications

 CD-ROM, DVD-ROM, CD-R/RW, DVD recorder, various combination types.

■ Package

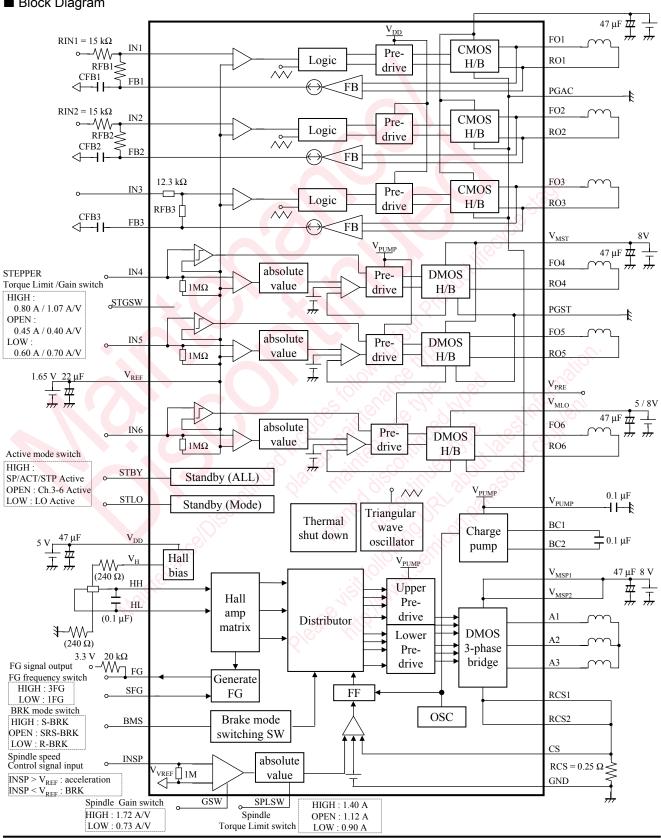
• 56 pin plastic small outline package with heat sink (SOP Type)

Type

• Bi-CDMOS IC.

Panasonic AN41240A

■ Block Diagram



■ Pin Descriptions

Pin No.	Pin name	Туре	Description		
1	V _{MSP2}	Power supply	Spindle motor drive power supply 2		
2	FO4	Output	Ch.4 non-inverting output		
3	RO4	Output	Ch.4 inverting output		
4	PGST	Ground	Ch.4, Ch.5 drive GND		
5	FO5	Output	Ch.5 non-inverting output		
6	RO5	Output	Ch.5 inverting output		
7	V _{MST}	Power supply	Ch.4, Ch.5 motor drive power supply		
8	BC1	Output	Charge pump setup capacitor 1		
9	BC2	Output	Charge pump setup capacitor 2		
10	V _{PUMP}	Output	Charge pump output		
11	GND	Ground	Control circuit GND		
12	IN4	Input	Ch.4 control signal input		
13	IN5	Input	Ch.5 control signal input		
14	V_{REF}	Input	Reference voltage input		
15	N.C.	-	N.C.		
16	INSP	Input	Spindle motor drive control signal input		
17	IN6	Input	Ch.6 control signal input		
18	IN2	Input	Ch.2 control signal input		
19	FB2	Output	Ch.2 feedback output		
20	V _{PRE}	Input	Ch.6 Pre-Drive power supply		
21	FB1	Output	Ch.1 feedback output		
22	IN1	Input	Ch.1 control signal input		
23	IN3	Input	Ch.3 control signal input		
24	FB3	Output	Ch.3 feedback output		
25	RO6	Output	Ch.6 inverting output		
26	V _{MLO}	Power supply	Ch.6 motor drive power supply		
27	FO6	Output	Ch.6 non-inverting output		
28	PGAC2	Ground	Ch.1, Ch.2, Ch.3, Ch.6 drive GND2		
29	RO3	Output	Ch.3 inverting output		
30	FO3	Output	Ch.3 non-inverting output		
31	RO2	Output	Ch.2 inverting output		
32	FO2	Output	Ch.2 non-inverting output		
33	PGAC1	Ground	Ch.1, Ch.2, Ch.3, Ch.6 drive GND1		
34	V_{MAC}	Power supply	Ch.1, Ch.2, Ch.3 coil drive power supply		
35	RO1	Output	Ch.1 inverting output		

■ Pin Descriptions (continued)

Pin No.	Pin name	Туре	Description					
36	FO1	Output	h.1 non-inverting output					
37	V_{H}	Output	indle motor drive hall bias output					
38	HL	Input	ndle motor drive hall element negative input					
39	НН	Input	Spindle motor drive hall element positive input					
40	V_{DD}	Power supply	Control circuit power supply					
41	FG	Output	indle motor drive FG signal output					
42	N.C.		C.					
43	SPLSW	Input	pindle motor Torque Limit switching input					
44	STGSW	Input	Ch.4, Ch.5 motor drive input/output Gain switching input					
45	BMS	Input	Spindle motor drive brake mode switching input					
46	GSW	Input	Spindle motor drive input/output Gain switching input					
47	SFG	Input	Spindle motor drive FG mode switching input					
48	STLO	Input	LO shutdown input					
49	STBY	Input	Total shutdown input					
50	V _{MSP1}	Power supply	Spindle motor drive power supply 1					
51	A1	Output	Spindle motor drive output 1					
52	CS	Input	Spindle motor drive output current detection					
53	RCS1	Output	Spindle motor drive common source output 1					
54	A2	Output	Spindle motor drive output 2					
55	A3	Output	Spindle motor drive output 3					
56	RCS2	Output	Spindle motor drive common source output 2					

■ Absolute Maximum Ratings

A No.	Parameter	Symbol	mbol Rating		Pin	Notes
1	Supply voltage	V _{DD} , V _{MAC}	V_{DD}, V_{MAC} 6.0			*1
1 Supply voltage		V _{MSP} , V _{MST} , V _{MLO}	10.0 V		_	1
		I_{DD}	100			
		I_{MSP}	1 500			
2	Supply current	I _{MAC}	2 500	mA	_	_
		I_{MST}	2 000		№ .	
		I_{MLO}	1 000		eta ^O	
3	Power dissipation	P_{D}	448	mW	_%_	*2
4	Operating ambient temperature	T_{opr}	-40 to +85	°C	"!!lecy -	*3
5	Storage temperature	$T_{\rm stg}$	-55 to +150	°C	11/C -	*3
6	Drive power supply / output instantaneous current spindle	$I_{(p)}$	±3 500	mA	p = 1, 50, 51, 53, 54, 55, 56	*4, *5
7	Drive output current Ch.1, Ch.2, Ch.3	I _(q)	±1 000	mA	q = 29, 30, 31, 32, 35, 36	*5
8	Drive output current Ch.4, Ch.5, Ch.6	$I_{(r)}$	±1 000	mA	r = 2, 3, 5, 6, 25, 27	*5
9	Drive output voltage	V _(m)	10.7	V	m = 2, 3, 5, 6, 25, 27, 51, 54, 55	*5
10	Drive output voltage	V _(l)	6.7	V	1 = 29, 30, 31, 32, 35, 36	*5
11	Control signal input voltage	V _(n)	GND to V_{DD}	SOLVIII.	n = 12, 13, 14, 16, 17, 18, 22, 23 38, 39, 43, 44, 45, 46 47, 48, 49	*5
12	Hall bias current	I _{HB(x)}	30	mA	x = 37	*5

Notes) *1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

The charge pump output circuit voltage will exceed the supply voltage. The limit of the charge pump output circuit voltage is shown in "Operating Supply Voltage / Current Range" on Page8.

- *2: The power dissipation shown is the value at T_a = 85°C for the independent (unmounted) IC package.

 When using this IC, refer to the P_D-T_a diagram of the package standard and use under the condition not exceeding the allowable value.
- *3: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for $T_a = 25$ °C.
- *4: Each output current of ±3 500 mA, ±2 000 mA is only permissible for a period within 1 ms and 50 ms respectively.
- *5: Do not apply current or voltage from outside to any pin not listed other than the power supply and ground pins. For the circuit currents, '+' denotes current flowing into the IC, and '-' denotes current flowing out of the IC.

■ Operating supply voltage range

Parameter	Symbol	Min	Тур	Max	Unit	Notes
	V_{DD}	4.5	5.0	5.5		_
	V _{MAC}	4.5	5.0	5.5	V	*
Supply voltage range	V _{MSP} , V _{MST}	7.2	8.0	8.8		
	V _{MLO} (5 V) V _{MLO} (8 V)	4.5 7.2	5.0 8.0	5.5 8.8		

Note) *: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

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